

**IN THE CLAIMS:**

Please cancel claims 1-32 without prejudice or disclaimer of the subject matter thereof, noting that claims 14, 15 and 25-32, which claims stand withdrawn from consideration, are canceled without prejudice to the right to file a divisional application directed thereto.

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Claims 1-32 (canceled)

[Please add the following new claims:]

33. (new) A semiconductor laser module comprising:  
a semiconductor laser;  
a driving circuit for driving said semiconductor laser; and  
a temperature control means for controlling the temperature of the semiconductor laser;

B' wherein said temperature control means includes a heating element for controlling temperature of said semiconductor laser, a temperature sensor for sensing ambient air temperature of said semiconductor laser, and a temperature module for controlling said heating element on the basis of temperature information from said temperature sensor so as to maintain said semiconductor laser at least at a temperature of the ambient air temperature of said semiconductor laser.

34. (new) A semiconductor laser module according to claim 33, wherein said temperature control module controls said heating element to maintain said semiconductor laser at a temperature higher than the ambient air temperature of said semiconductor laser.

35. (new) A semiconductor laser module according to claim 34, wherein said semiconductor laser is mounted on said heating element through an insulating

film for electrically separating the heat element from said semiconductor laser so as to be thermally combined, and a laminated thin film is provided for joining said semiconductor laser to said insulating film.

36. (new) A semiconductor laser module according to claim 34, wherein said semiconductor laser and said heating element are molded into a plastic module, and the ambient temperature is air temperature outside of said module.

37. (new) A semiconductor laser module according to claim 34, further comprising a supporting substrate, said semiconductor laser, said heating element and said temperature sensor being mounted on said supporting substrate, wherein said heating element controls a temperature of said supporting substrate together with said semiconductor laser.

38. (new) A semiconductor laser module according to claim 34, wherein said semiconductor laser is a Fabry-Perot type laser.

39. (new) A semiconductor laser according to claim 34, wherein said semiconductor laser is a modulator integrated laser.

40. (new) A semiconductor laser module according to claim 37, wherein said semiconductor laser, said heating element and said temperature sensor are mounted on a main surface of said supporting substrate, wherein a main surface of a semiconductor chip of said semiconductor laser, on which a joining for emitting laser light has been formed, is disposed on said main surface of said supporting substrate, and wherein said heating element is disposed in proximity to said joining on said

main surface of said semiconductor chip of said semiconductor laser on said main of said supporting substrate.

41. (new) A semiconductor laser module according to claim 39, wherein said heating element is disposed between a main surface of a semiconductor chip of said semiconductor laser and a main surface of said supporting substrate.

42. (new) A semiconductor laser module according to claim 33, wherein said semiconductor laser is maintained at least at the temperature of the ambient air temperature of said semiconductor laser only by controlling said heating element.